

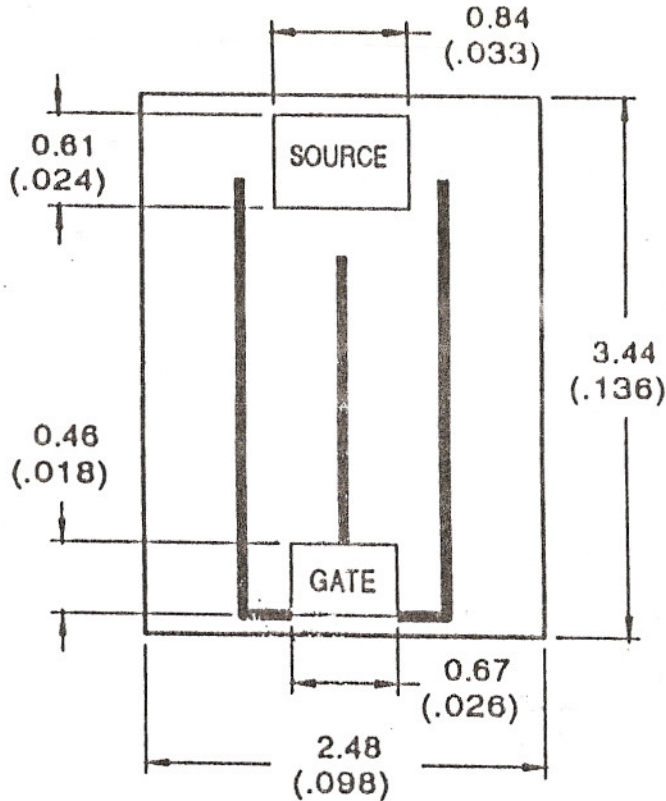


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



HEX-2: 400V TO 500V, N-CHANNEL

Topside Metal: Al
 Backside: ChAgNi
 Backside Potential: Drain
 Mask Ref:
 Bond Pads: .004" min

APPROVED BY: CB
 MFG: IRI

DIE SIZE: .136" x .098"
 THICKNESS: .017"

DATE: 2/8/01
 P/N: IRFC320